



Material Content Data Sheet



Sales Product Name				BSZ160N10NS3 G		Issued		20. July 2018	
MA#				MA001493838					
Package				PG-TSDSON-8-2		Weight*		40.21 mg	
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	inorganic material	silicon	7440-21-3	1.835	4.56	4.56	45635	45635	
leadframe	inorganic material	phosphorus	7723-14-0	0.002	0.01		52		
	non noble metal	zinc	7440-66-6	0.008	0.02		208		
	non noble metal	iron	7439-89-6	0.168	0.42		4170		
wire	non noble metal	copper	7440-50-8	6.808	16.93	17.38	169315	173745	
	non noble metal	copper	7440-50-8	0.041	0.10	0.10	1027	1027	
	encapsulation	organic material	carbon black	1333-86-4	0.037	0.09		909	
encapsulation	plastics	epoxy resin	-	1.882	4.68		46815		
	inorganic material	silicondioxide	60676-86-0	16.356	40.70	45.47	406792	454516	
leadfinish	non noble metal	tin	7440-31-5	0.387	0.96	0.96	9629	9629	
plating	noble metal	silver	7440-22-4	0.963	2.39	2.39	23940	23940	
solder	non noble metal	tin	7440-31-5	0.037	0.09		915		
	noble metal	silver	7440-22-4	0.046	0.11		1144		
	non noble metal	lead	7439-92-1	1.758	4.37	4.57	43714	45773	
heatspreader	inorganic material	phosphorus	7723-14-0	0.001	0.00		27		
	non noble metal	zinc	7440-66-6	0.004	0.01		107		
	non noble metal	iron	7439-89-6	0.086	0.21		2145		
	non noble metal	copper	7440-50-8	3.501	8.71	8.93	87078	89357	
heat sink CLIP	inorganic material	phosphorus	7723-14-0	0.002	0.00		47		
	non noble metal	zinc	7440-66-6	0.008	0.02		188		
	non noble metal	iron	7439-89-6	0.151	0.38		3753		
	non noble metal	copper	7440-50-8	6.127	15.24	15.64	152390	156378	
*deviation	< 10%			Sum in total:		100.00		1000000	

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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